

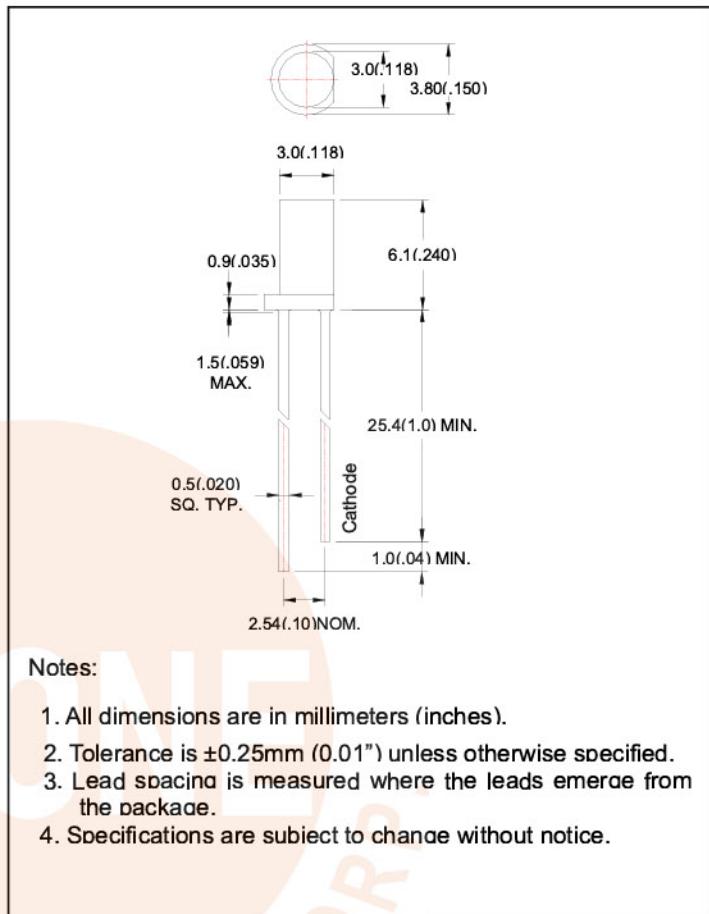
● Features:

1. Chip material: GaP/GaP
2. Emitted color : Green
3. Lens Appearance : Green Diffused
4. Cylindrical shape.
5. Low power consumption.
6. Compatible
7. Long life solid state reliability.
8. This product don't contain restriction substance. compliance ROHS standard.

● Applications:

1. TV set
2. Monitor
3. Telephone
4. Computer
5. Circuit board

● Package dimensions:



● Absolute Maximum Ratings($T_a=25^\circ\text{C}$)

Parameter	Symbol	Rating	Unit
Power Dissipation	Pd	80	mW
Forward Current	I _F	30	mA
Peak Forward Current ^{*1}	I _{FP}	150	mA
Reverse Voltage	V _R	5	V
Operating Temperature	T _{OOP}	-40°C~80°C	
Storage Temperature	T _{STA}	-40°C~85°C	
Soldering Temperature	T _{SOL}	260°C(for 5 seconds)	

^{*1}Condition for I_{FP} is pulse of 1/10 duty and 0.1msec width.

● Electrical and optical characteristics($T_a=25^{\circ}\text{C}$)

Parameter	Symbol	Condition	Min.	Tvp.	Max.	Unit
Forward Voltage	V_F	$I_F=20\text{mA}$	-	2.2	2.6	V
Luminous Intensity	I_v	$I_F=20\text{mA}$	-	8.0	-	mcd
Reverse Current	I_R	$V_R=5\text{V}$	-	-	100	μA
Peak Wave Lenath	λ_p	$I_F=20\text{mA}$	-	568	-	nm
Dominant Wave Lenath	λ_d	$I_F=20\text{mA}$	560	-	576	nm
Spectral Line Half-width	$\Delta\lambda$	$I_F=20\text{mA}$	-	30	-	nm
Viewing Angle	$2\theta_{1/2}$	$I_F=20\text{mA}$	-	130	-	deg

● Typical Electro-Optical Characteristics Curves

Fig.1 Relative intensiy vs. Wavelength

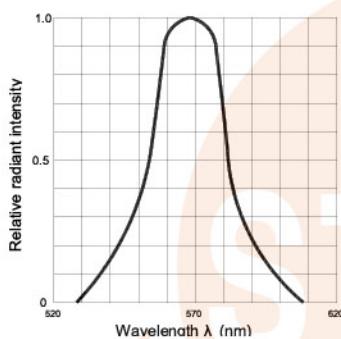


Fig.2 Forward current derating curve vs. Ambient temperature

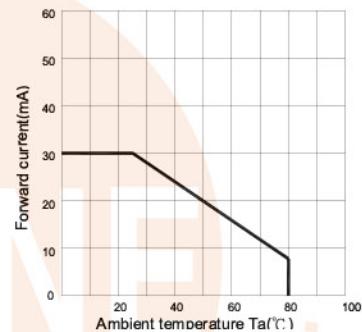


Fig.3 Forward current vs. Forward voltage

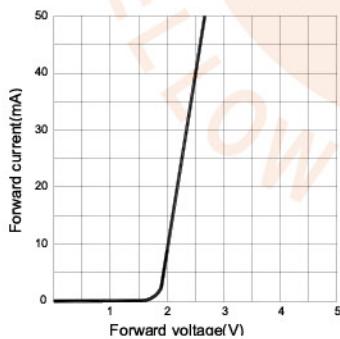


Fig.4 Relative luminous intensity vs. Ambient temoperature

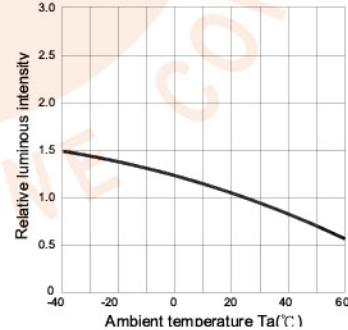


Fig.5 Relative luminous intensiv vs. Forward current

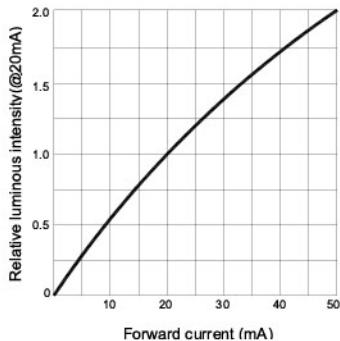
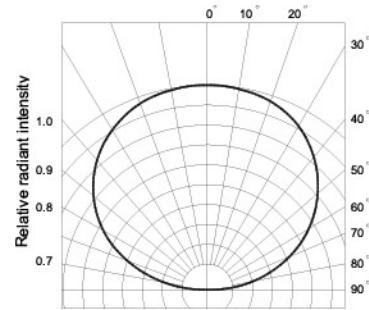
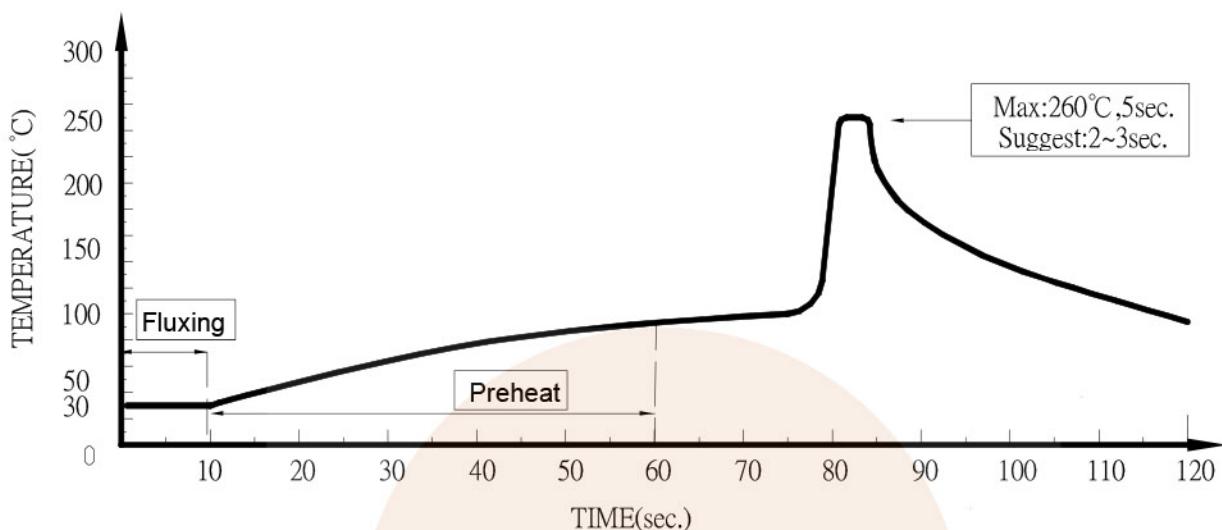


Fig.6 Radiation diafram



● Dip Soldering



1. Please avoid any external stress applied to the lead-frames and epoxy while the LEDs are at high temperature, especially during soldering
2. DIP soldering and hand soldering should not be done more than one time.
3. After soldering, avoid the epoxy lens from mechanical shock or vibration until the LEDs are back to room temperature.
4. Avoid rapid cooling during temperature ramp-down process
5. Although the soldering condition is recommended above, soldering at the lowest possible temperature is feasible for the LEDs

● IRON Soldering

300°C Within 3 sec., One time only.